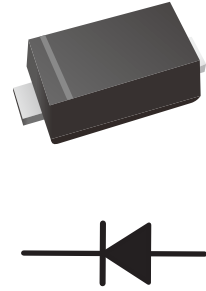


Surface Mount Schottky Barrier Rectifier

Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end

Ordering Information

Part Number	Marking	Shipping	Reel
LT3F40-TR3	3F40 or SSL34	3000PCS Tape&Reel	7 inches
LT3F40-TR10	3F40 or SSL34	10000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %.

Parameter	Symbol	LT3F40	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Maximum RMS voltage	V_{RMS}	28	V
Maximum DC Blocking Voltage	V_{DC}	40	V
Maximum Average Forward Rectified Current @ Fig.1	$I_{F(AV)}$	3	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	80	A
Maximum Instantaneous Forward Voltage at 3 A	V_F	0.45	V
Maximum DC Reverse Current $T_a = 25\text{ }^{\circ}\text{C}$ at Rated DC Blocking Voltage $T_a = 100\text{ }^{\circ}\text{C}$	I_R	0.3 5	mA
Typical Junction Capacitance (Note1)	C_j	215	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	100 20 30	$^{\circ}\text{C/W}$
Operating Junction Temperature Range	T_j	-55 ~ +150	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-55 ~ +150	$^{\circ}\text{C}$

Note: (1) Measured at 1 MHz and applied reverse voltage of 4V DC.

(2) PCB mounted with 2.0" X 2.0" (5cm X 5cm) copper pad areas.

Characteristics Curves

Fig.1 Forward Current Derating Curve

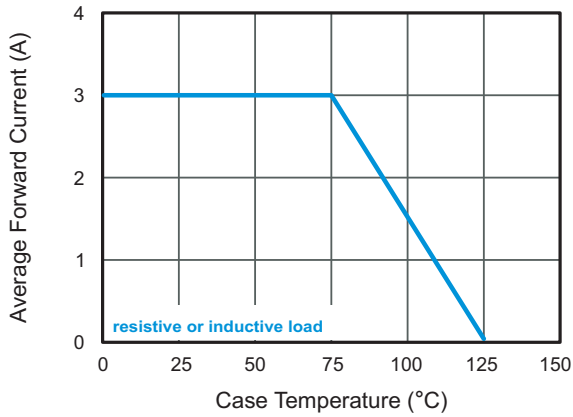


Fig.2 Typical Reverse Characteristics

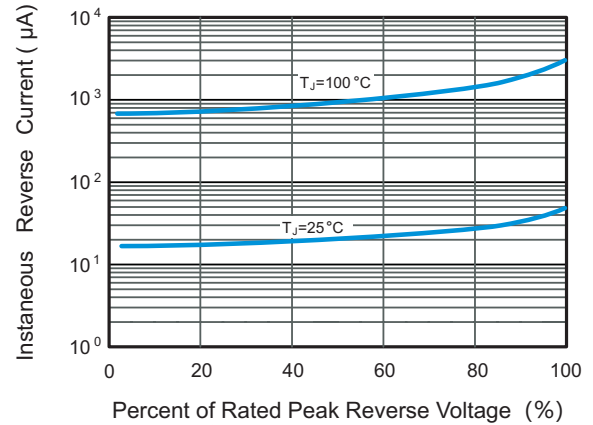


Fig.3 Typical Forward Characteristic

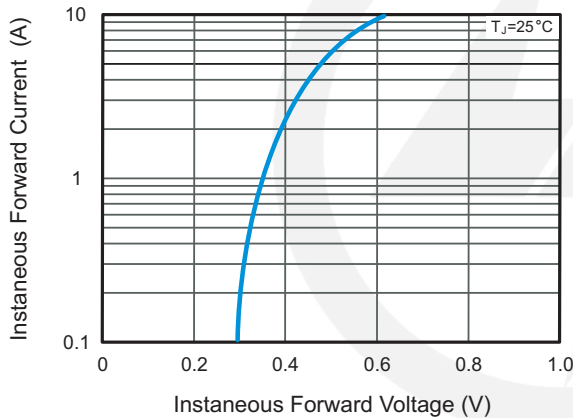


Fig.4 Typical Junction Capacitance

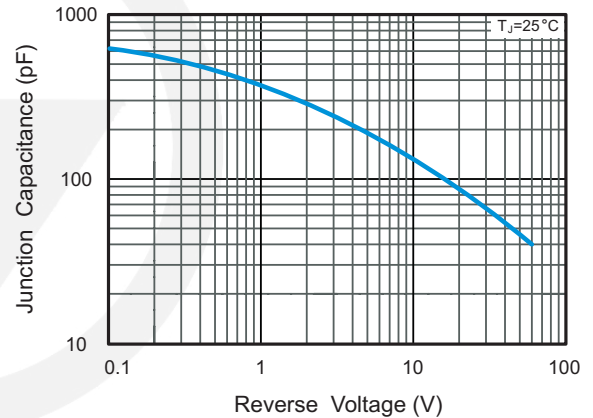
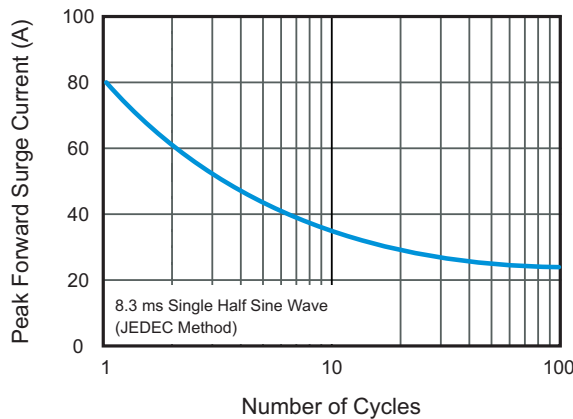
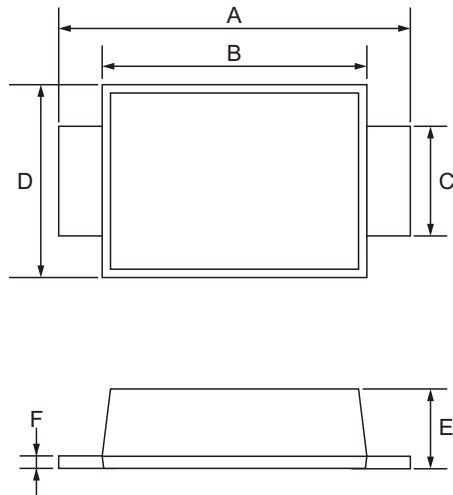


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



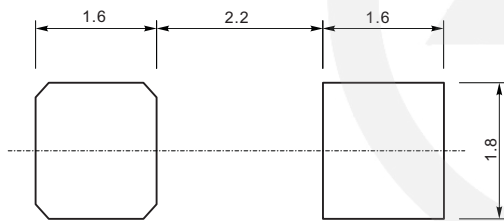


SMAF Package Outline



SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	4.40	4.90
B	3.30	3.70
C	1.30	1.60
D	2.40	2.70
E	0.90	1.20
F	0.12	0.20

SMAF Suggested Pad Layout

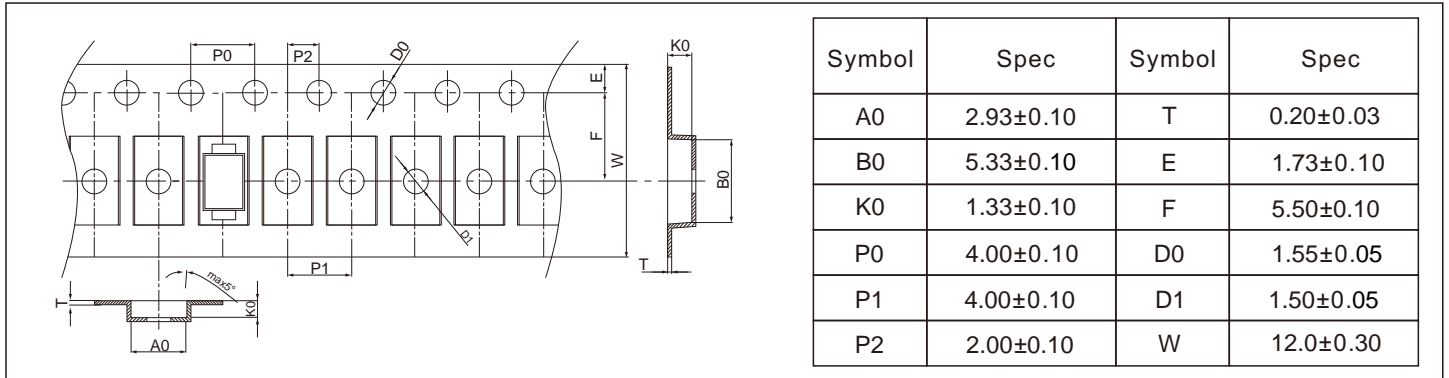


Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purpose only.

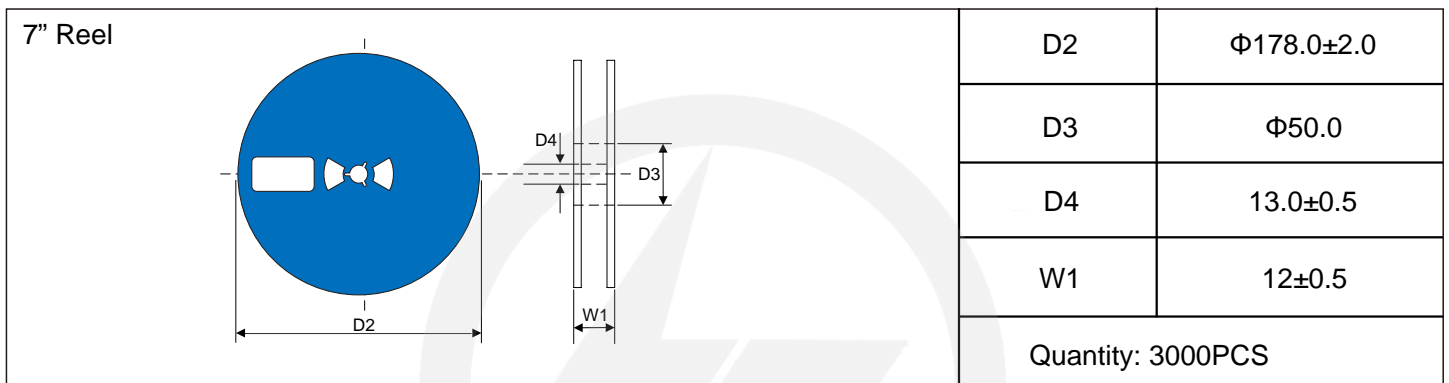
Carrier Tape Dimensions

Unit : mm



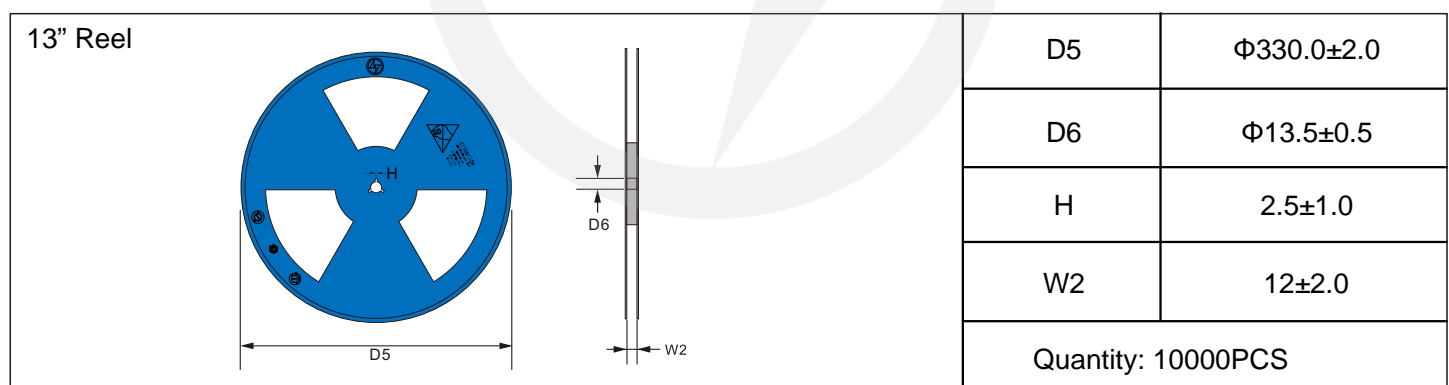
Reel Dimensions

Unit : mm

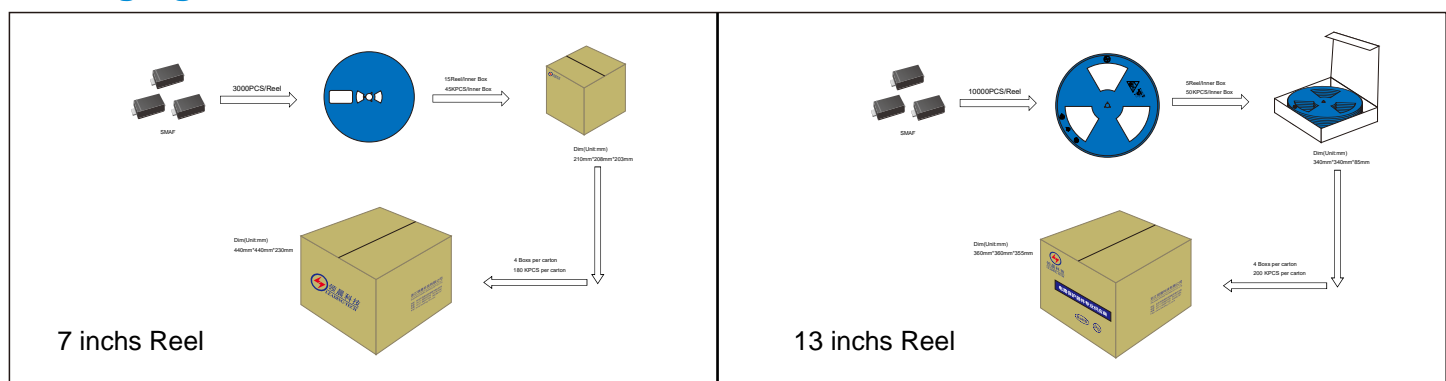


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2024.3.18	2024.3.18	3.0	New File	/	Ding	
02	2025.06.11	2025.06.11	3.1	Update packaging information	/	Ding	